



<b>Processor Family</b>	CC = Embedded RF Radio MSP = Mixed Signal Processor XMS = Experimental Silicon	
<b>430 MCU Platform</b>	TI's Low Power Microcontroller Platform	
<b>Device Type</b>	<b>Memory Type</b> C = ROM F = FLASH FR = FRAM G = FLASH L = No nonvolatile memory	<b>Specialized Application</b> AFE = Analog front end BT = Bluetooth® BQ = Contactless power CG = ROM medical FE = Flash energy meter FG = Flash medical FW = Flash electronic flow meter
<b>Series</b>	1 Series = Up to 8 MHz 2 Series = Up to 16 MHz 3 Series = Legacy OTP 4 Series = Up to 16 MHz w/ LCD	5 Series = Up to 25 MHz 6 Series = Up to 25 MHz w/ LCD 0 = Low-voltage series
<b>Feature Set</b>	Various levels of integration within a series	
<b>Optional: A = Revision</b>	N/A	
<b>Optional: Temperature Range</b>	S = 0°C to 50°C C = 0°C to 70°C I = -40°C to 85°C T = -40°C to 105°C	
<b>Packaging</b>	<a href="http://www.ti.com/packaging">www.ti.com/packaging</a>	
<b>Optional: Distribution Format</b>	T = Small reel (7 in) R = Large reel (11 in) No markings = Tube or tray	
<b>Optional: Additional Features</b>	Q1 = Automotive qualified EP = Enhanced product (-40°C to 105°C) HT = Extreme temperature parts (-55°C to 150°C)	